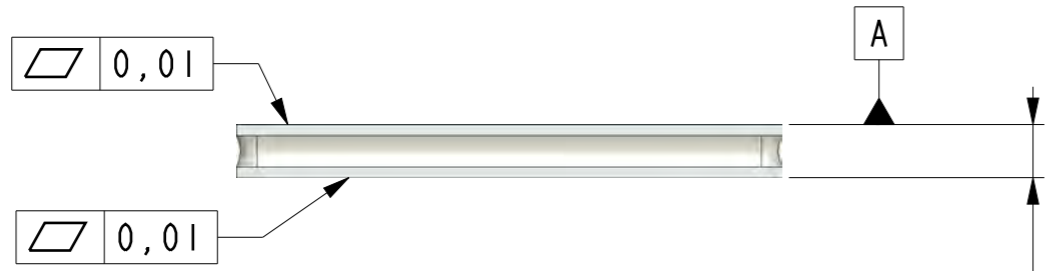
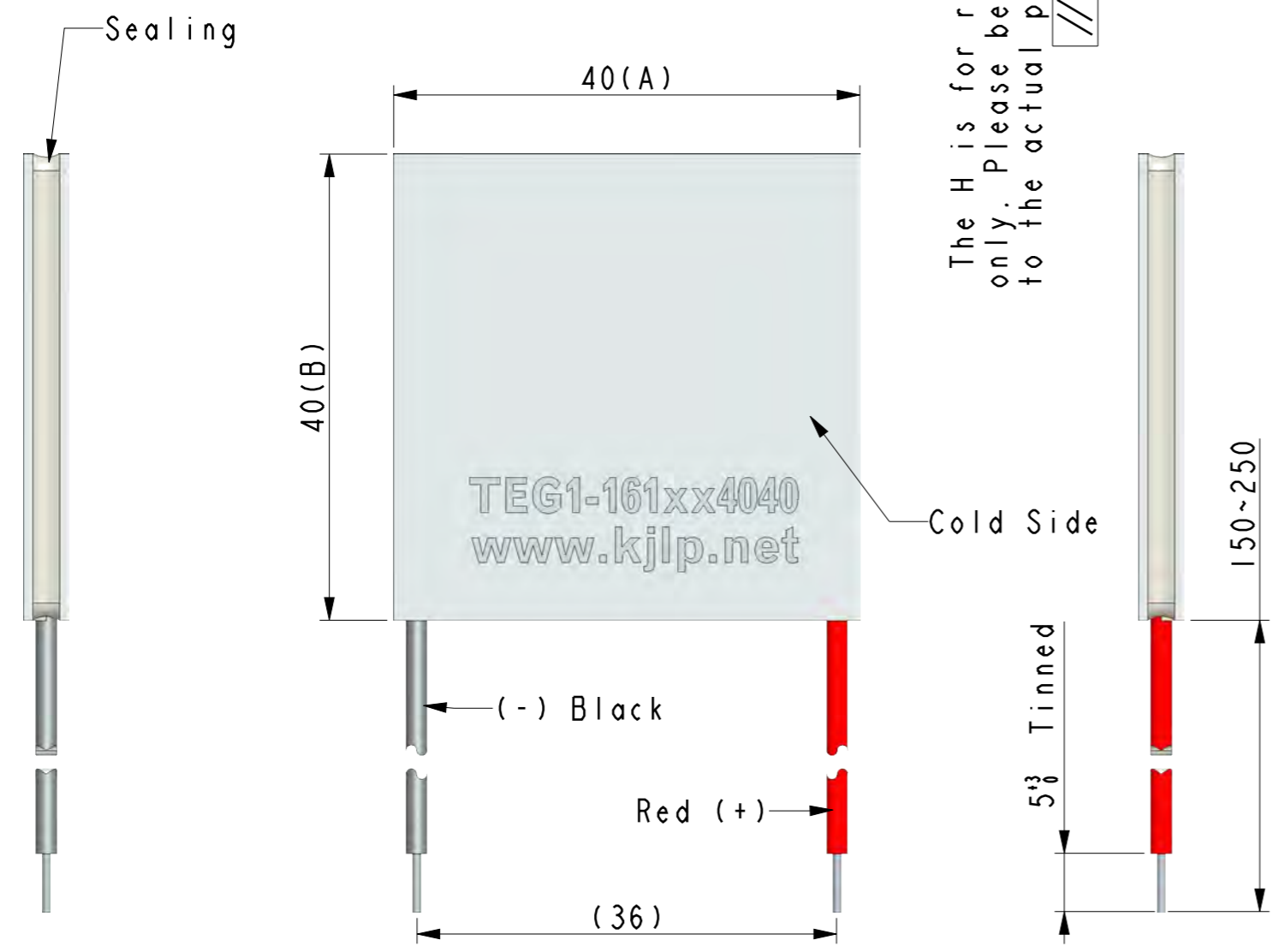
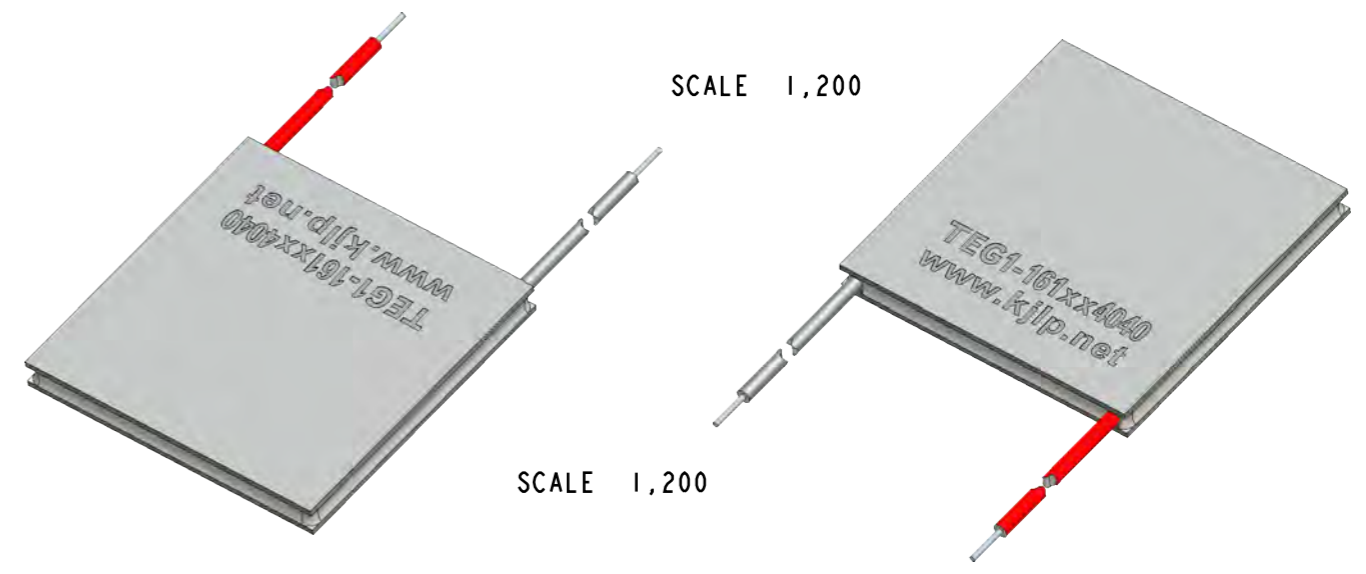


REVISIONS						
REV.	POS.	DESCRIPTION	DATE	DRW	APP	ECR#
A		INITIAL CREATION	2013/01/01	Gary	Mason	



(H)±0.1
The H is for reference only. Please be subject to the actual products.
// 0,05 A



Part Number And Feature:

T	E	G	I	-	1	6	1	x	x	4	0	4	0	Sealing	YES
	∇		∇			∇		∇		∇		∇		Operation Temperatur(Max.)	200°C(Max.)
Thermo	Electric	Chip	Stage	Stack	N & P	Stack	Quantity	R	Load	Dimension (A)	Dimension (B)			Melting Point	235°C
														Storage Temperature	-60°C~100°C
														RoHS	YES

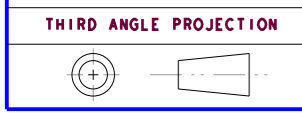
Technical Data:

ITEM	Part NO.	Stack(P&N)	U Load(Max.)	P Load(Max.)	R Load(Max.)	Uoc	P/N Size	DIM(A)	DIM(B)	DIM(H)
1	TEG1-161684040	241	3.55 V	7.6 W	6.8 Ohm	6.7 V	2.0*1.2*1.2	40	40	RF4.2

Notes:

1. Printing always on cold side.
2. Tolterance of thermo and electric parameters ±10%.
3. Please mount heat sink before you use it. also, please do not exceed the extra voltage at any time.

*DO NOT SCALE DRAWING



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USED OR DISCLOSED OR IN PART TO ANYONE WITHOUT THE PERMISSION OF KJLP (SHENZHEN) ELECTRONICS
CO., LTD.

1. UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE MM
2 TOLERANCE ARE AS FOLLOWS:
0 < X < 2 ± 0.06
2 < X < 10 ± 0.08
10 < X < 50 ± 0.12
50 < X < 100 ± 0.16
100 < X < 200 ± 0.20
200 < X < 300 ± 0.30
ANGLES ± 0.5°

PART NO.	TEG1-161xx4040		DESCRIPTION	161 P&N, 7.6W(Max.), 40*40mm				
	SIGNATURE	DATE		昆晶冷片(深圳)电子有限公司 KJLP (SHENZHEN) ELECTRONICS CO., LTD email: kjlp@kjlp.net http:// www.kjlp.net Tel: +86-755-82528352 Fax: +86-755-22639899				
DRAWN BY	Gary	2013/01/01		CAD MODLE:	TEG1-161xx4040.prt	SCALE: 1:1	REV: A	
CHECKED BY	Justin	2013/01/01			CAD DWG:			TEG1-161xx4040.drw
ENGR	Vivi	2013/01/01			SIZE: A3			SHEET: 1 OF 1
APPROVED BY	Mason	2013/01/01						
MATERIAL:	ISSUED BY	Jack	2013/01/01					